DB27309

Silicon epitaxial planar type

For high speed switching circuits DB2S309 in SSSMini2 type package

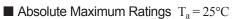
Features

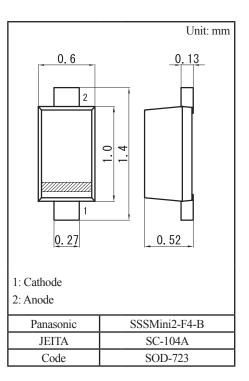
- \bullet Short reverse recovery time $t_{\rm rr}$
- \bullet Small reverse current I_{R}
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL: Level 1 compliant)
- Marking Symbol: C5

Packaging

DB2730900L Embossed type (Thermo-compression sealing): 10000 pcs / reel (standard)

eter Symbol Rating		Unit	
V _R	30	V	
V _{RRM}	30	V	
I _{F(AV)}	100	mA	
I _{FM}	200	mA	
I _{FSM}	1	А	
Tj	125	°C	
T _{opr}	-40 to +85	°C	
T _{stg}	-55 to +125	°C	
	V_{R} V_{RRM} $I_{F(AV)}$ I_{FM} I_{FSM} T_{j} T_{opr}	$\begin{tabular}{ c c c c c c c } \hline V_R & 30 \\ \hline V_{RRM} & 30 \\ \hline I_{F(AV)} & 100 \\ \hline I_{FM} & 200 \\ \hline I_{FSM} & 1 \\ \hline T_j & 125 \\ \hline T_{opr} & -40 \text{ to } +85 \\ \hline \end{tabular}$	





Note) *1: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

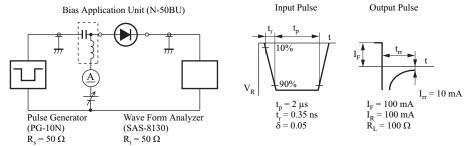
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

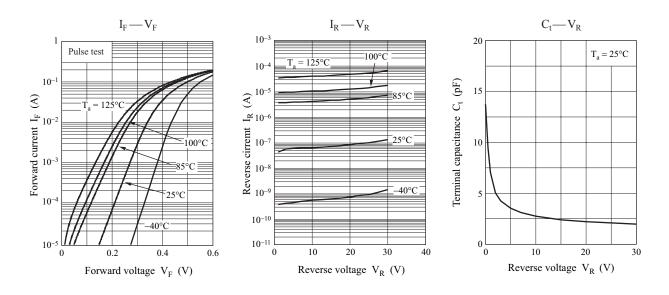
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	V_{F1}	$I_F = 10 \text{ mA}$			0.44	v
	V _{F2}	$I_F = 100 \text{ mA}$			0.58	
Reverse current	I _{R1}	$V_{\rm R} = 10 {\rm V}$			0.3	μA
	I _{R2}	$V_R = 30 V$			2.0	
Terminal capacitance	Ct	$V_{\rm R} = 10 \text{ V}, \text{ f} = 1 \text{ MHz}$		3.0		pF
Reverse recovery time *1	t _{rr}	$I_{\rm F} = I_{\rm R} = 100 \text{ mA}, I_{\rm rr} = 10 \text{ mA}, R_{\rm L} = 100 \Omega$		1.3		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

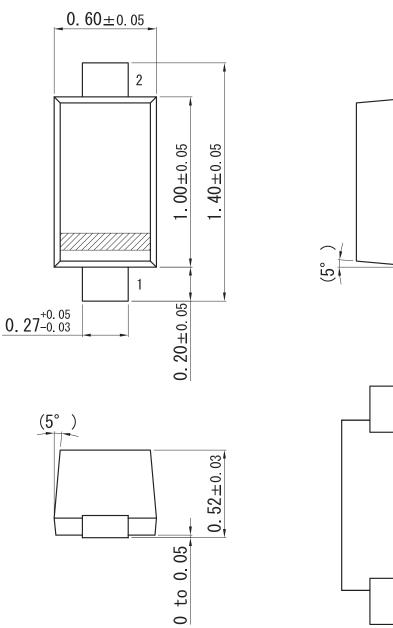
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

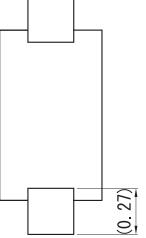
- 3. Absolute frequency of input and output is 250 MHz
 - *1: trr measurement circuit



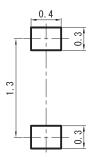








Land Pattern (Reference) (Unit: mm)



Unit: mm

0.13^{+0.05}

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